

WIRE TO BOARD WAFER P=1.2mm TOP ENTRY CONNECTOR

1. INTRODUCTION

1.1. Purpose

Testing was performed on the Tyco Electronics WIRE TO BOARD WAFER P=1.2mm TOP ENTRY CONNECTOR to determine its conformance to the requirements of Product Specification 108-57767.

1.2. Scope

This report covers the electrical, mechanical, and environmental performance of the Tyco Electronics WIRE TO BOARD WAFER P=1.2mm TOP ENTRY CONNECTOR.

1.3. Conclusion

The Tyco Electronics WIRE TO BOARD WAFER P=1.2mm TOP ENTRY CONNECTOR meets the electrical, mechanical, and environmental performance requirements of Product Specification 108-57767.

1.4. Product description

The WIRE TO BOARD WAFER P=1.2mm TOP ENTRY CONNECTOR is designed for printed circuit board applications. The contacts are copper alloy, Gold plated on the contact interface and Gold plating on the soldertail, all over nickel under-plated. The housing material is glass filled insulating polymer, UL94V-0.

1.5. Test samples

Test specimens were randomly selected from normal current production lots, and the following Product were used for test :

| Test Group | Quantity | Description | Part Number |
|---------------------------|----------|----------------------------------|---|
| A, B, C, D, E, F, G, H, I | 5EA. | WTB P=1.2mm TOP ENTRY CONNECTOR. | 1909782-*(Plug) 1909783-*(Rec. Housing) 1909784-*(Rec. Contact) |

1.6. Qualification test sequence

| Test or Examination | Test Group | | | | | | | | |
|---------------------------------|---------------------|-----|-----|-----|-----|-----|-----|-----|-------|
| | A | B | C | D | E | F | G | H | I |
| | Test Sequence (a) | | | | | | | | |
| Examination of Product | 1,7 | 1,3 | 1,6 | 1,9 | 1,5 | 1,5 | 1,9 | 1,3 | 1,3,5 |
| Contact Resistance | 2,8 | | 2,5 | 4,6 | 2,4 | 2,4 | 4,6 | | |
| Dielectric withstanding Voltage | | | | 3,8 | | | 3,8 | | |
| Insulation Resistance | | | | 2,7 | | | 2,7 | | |
| Temperature Rising | | 2 | | | | | | | |
| Mating Force | 3,6 | | | | | | | | |
| Un-mating Force | 4,7 | | | | | | | | |
| Durability | 5 | | | | | | | | |
| Vibration | | | 4 | | | | | | |
| Mechanical Shock | | | 3 | | | | | | |
| Solder ability | | | | | | 3 | | | |
| Resistance to Soldering Heat | | | | | | | | | 2,4 |
| Thermal Shock | | | | | 3 | | | | |
| Humidity Temperature Cycling | | | | 5 | | | | | |
| Temperature Life | | | | | | | 5 | | |
| Salt Spray | | | | | | | | 2 | |

NOTE : (a) Numbers indicate sequence in which tests are performed.

(b) Discontinuities shall not take place in this test group, during tests.

Figure 1

2. TEST RESULT

| GP | TEST | Requirement | TEST DATA | | | | Judgment |
|----|---------------------------------|-----------------------------|--------------------|------|------|-----------|----------|
| | | | Max. | Min. | Mean | Std. Dev. | |
| A | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 10.2 | 8.5 | 9.5 | 0.62 | ACCEPTED |
| | Mating Force | See Note1. | PASSED (See Note1) | | | | ACCEPTED |
| | Un-mating Force | See Note1. | PASSED (See Note1) | | | | ACCEPTED |
| | Durability | 50 Cycles | PASSED | | | | ACCEPTED |
| | Mating Force | See Note 1. | PASSED (See Note1) | | | | ACCEPTED |
| | Un-mating Force | See Note 1. | PASSED (See Note1) | | | | ACCEPTED |
| | Contact Resistance | 40mΩ Max. | 12.1 | 9.2 | 10.8 | 1.08 | ACCEPTED |
| B | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Temperature Rising | 30°C Max. | 15 | 11 | 13.2 | 1.48 | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| C | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 9.9 | 7.6 | 8.1 | 1.01 | ACCEPTED |
| | Mechanical Shock | 50G, 11msec. | PASSED | | | | ACCEPTED |
| | Vibration | 10-55-10 Hz | PASSED | | | | ACCEPTED |
| | Contact Resistance | 40 mΩ Max. | 10.1 | 8.2 | 8.6 | 0.83 | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| D | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Insulation Resistance | 100 MΩ Min. | PASSED | | | | ACCEPTED |
| | Dielectric withstanding Voltage | 500VAC, 1Minute | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 9.9 | 7.1 | 8.2 | 1.08 | ACCEPTED |
| | Humidity Temperature Cycling | 25~65°C, 90~95%RH, 10cycles | PASSED | | | | ACCEPTED |
| | Contact Resistance | 40 mΩ Max. | 10.1 | 7.9 | 8.6 | 0.88 | ACCEPTED |
| | Insulation Resistance | 100 MΩ Min. | PASSED | | | | ACCEPTED |
| | Dielectric withstanding Voltage | 500 VAC, 1Minute | PASSED | | | | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |

Figure 2 (Cont.)

| GP | TEST | Requirement | DATA | | | | Judgment |
|----|---------------------------------|---|--------|------|------|-----------|----------|
| | | | Max. | Min. | Mean | Std. Dev. | |
| E | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 9.8 | 8.6 | 8.8 | 0.54 | ACCEPTED |
| | Thermal Shock | -55°C/+85°C, 5 Cycles | PASSED | | | | ACCEPTED |
| | Contact Resistance | 40 mΩ Max. | 10.2 | 8.5 | 8.9 | 0.72 | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| F | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 9.5 | 8.4 | 8.9 | 0.40 | ACCEPTED |
| | Solder ability | 95% Min. coverage | PASSED | | | | ACCEPTED |
| | Contact Resistance | 40 mΩ Max. | 10.5 | 8.6 | 9.8 | 0.72 | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| G | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Insulation Resistance | 100 MΩ Min. | PASSED | | | | ACCEPTED |
| | Dielectric withstanding Voltage | 500 VAC, 1Minute | PASSED | | | | ACCEPTED |
| | Contact Resistance | 20 mΩ Max. | 9.8 | 7.0 | 8.2 | 1.07 | ACCEPTED |
| | Temperature Life | 85°C, 250Hrs | PASSED | | | | ACCEPTED |
| | Contact Resistance | 40 mΩ Max. | 12.5 | 7.5 | 9.8 | 2.05 | ACCEPTED |
| | Insulation Resistance | 100 MΩ Min. | PASSED | | | | ACCEPTED |
| | Dielectric withstanding Voltage | 500 VAC, 1Minute | PASSED | | | | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| H | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Salt Spray | 35°C, 5%Salt, 48hours | PASSED | | | | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| I | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Resistance to Solder Heat | 150~180°C, 90±30sec 230°C Min., 30±10sec Peak Temp.: 260+0/-5°C | PASSED | | | | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |
| | Resistance to Solder Heat | 150~180°C, 90±30sec 230°C Min., 30±10sec Peak Temp.: 260+0/-5°C | PASSED | | | | ACCEPTED |
| | Examination of Product | No abnormalities | PASSED | | | | ACCEPTED |

Figure 2 (End)

NOTE 1.**Initial test result**

| NO.OF PIN. | Initial | | | | | | | |
|------------|---------|------|------|------|----------|------|------|------|
| | MATING | | | | UNMATING | | | |
| | Min | Max | Avg. | Std | Min | Max | Avg. | Std |
| 2PIN | 0.37 | 0.53 | 0.45 | 0.06 | 0.30 | 0.34 | 0.33 | 0.02 |
| 3PIN | 0.40 | 0.66 | 0.50 | 0.10 | 0.31 | 0.40 | 0.35 | 0.04 |
| 4PIN | 0.44 | 0.63 | 0.52 | 0.09 | 0.34 | 0.47 | 0.41 | 0.05 |
| 5PIN | 0.38 | 0.60 | 0.46 | 0.09 | 0.34 | 0.47 | 0.41 | 0.05 |
| 6PIN | 0.31 | 0.47 | 0.41 | 0.07 | 0.36 | 0.40 | 0.38 | 0.02 |

Unit: kgf

Finial test result

| NO.OF PIN. | Final | | | | | | | |
|------------|--------|------|------|------|----------|------|------|------|
| | MATING | | | | UNMATING | | | |
| | Min | Max | Avg. | Std | Min | Max | Avg. | Std |
| 2PIN | 0.35 | 0.47 | 0.42 | 0.08 | 0.18 | 0.28 | 0.24 | 0.04 |
| 3PIN | 0.34 | 0.46 | 0.38 | 0.05 | 0.24 | 0.29 | 0.26 | 0.02 |
| 4PIN | 0.28 | 0.35 | 0.32 | 0.03 | 0.18 | 0.27 | 0.23 | 0.03 |
| 5PIN | 0.32 | 0.39 | 0.35 | 0.03 | 0.18 | 0.39 | 0.31 | 0.09 |
| 6PIN | 0.29 | 0.43 | 0.36 | 0.06 | 0.17 | 0.36 | 0.28 | 0.08 |

Unit: kgf